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Kuncan 2835  
8/30/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Cho, Sung Dae  
Assignee: Samsung Electronics Co., Ltd.  
Title: Reel-Deployed Printed Circuit Board And Method For Manufacturing  
Chip-On-Board Packages  
Serial No.: 09/827,112 Filing Date: April 5, 2001  
Examiner: To be assigned Group Art Unit: To be assigned  
Docket No.: AB-698-1D US

Newport Beach, California  
June 29, 2001

COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR § 1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, the documents listed on the accompanying PTO Form-1449 are called to the attention of the Examiner for the above patent application. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above;

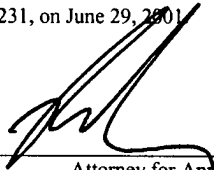
or

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3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

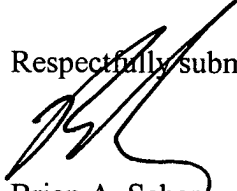
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on June 29, 2001.



Attorney for Applicant(s)

June 29, 2001  
Date of Signature

Respectfully submitted,



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